

# **General Description**

The WST3414 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WST3414 meet the RoHS and Green Product requirement with full function reliability approved.

#### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

# **Product Summery**

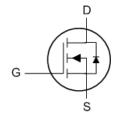
BVDSS	RDSON	ID
20V	24mΩ	6.0A

# **Applications**

- High Frequency Point-of-Load Synchronous Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

## **SOT-23-3L Pin Configuration**





## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
$V_{DS}$	Drain-Source Voltage	20	V	
$V_{GS}$	Gate-Source Voltage	±12	V	
I <sub>D</sub> @T <sub>c</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	6.0	А	
I <sub>D</sub> @T <sub>c</sub> =70℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	4.8	Α	
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	20	А	
P <sub>D</sub> @T <sub>A</sub> =25°C	Total Power Dissipation <sup>3</sup>	1	W	
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	$^{\circ}$	
TJ	Operating Junction Temperature Range -55 to 150		$^{\circ}$	

# **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>0JA</sub>	Thermal Resistance Junction-ambient <sup>1</sup>		125	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case <sup>1</sup>		80	°C/W



# Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =1mA		0.018		V/°C
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =4A		24	30	mΩ
		$V_{GS}$ =2.5 $V$ , $I_D$ =3 $A$		30	38	
$V_{GS(th)}$	Gate Threshold Voltage	)/ -\/   -250\	0.5	0.7	1.0	٧
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$V_{GS}=V_{DS}$ , $I_D=250uA$		-3.1		mV/℃
	Drain-Source Leakage Current	$V_{DS}$ =16V , $V_{GS}$ =0V , $T_J$ =25 $^{\circ}$ C			1	
I <sub>DSS</sub>		V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55℃			5	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm$ 12 $V$ , $V_{DS}$ =0 $V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =4A		20		S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.5	3	Ω
$Q_g$	Total Gate Charge (4.5V)	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =4A		8.6	12.0	nC
Q <sub>gs</sub>	Gate-Source Charge			1.37	1.9	
$Q_gd$	Gate-Drain Charge			2.3	3.2	
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DS}$ =10V , $V_{GS}$ =4.5V , $R_{G}$ =3.3 $\Omega$		5.2	10.4	
Tr	Rise Time			34	61	
T <sub>d(off)</sub>	Turn-Off Delay Time			23	46	ns
T <sub>f</sub>	Fall Time			9.2	18.4	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		635	889	
C <sub>oss</sub>	Output Capacitance			70	98	pF
C <sub>rss</sub>	Reverse Transfer Capacitance			63	88	1

# **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,4</sup>	V =V =0V Force Current			5.0	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			20	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃			1.2	V
t <sub>rr</sub>	Reverse Recovery Time			7.5		nS
Qrr	Reverse Recovery Charge	IF=4A , dI/dt=100A/ $\mu$ s , T $_{J}$ =25 $^{\circ}$ C		2.1		nC

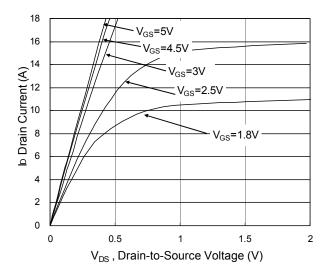
#### Note

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3.The power dissipation is limited by 150 ℃ junction temperature
- 4. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



**N-Ch MOSFET** 

# **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

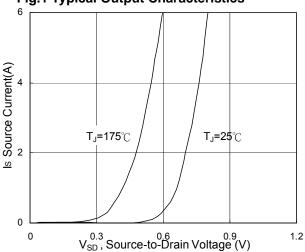


Fig.3 Forward Characteristics Of Reverse

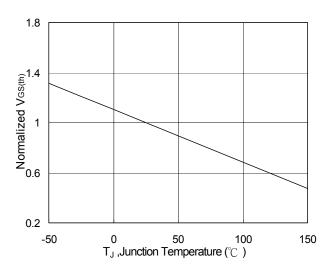


Fig.5 Normalized V<sub>GS(th)</sub> vs. T<sub>J</sub>

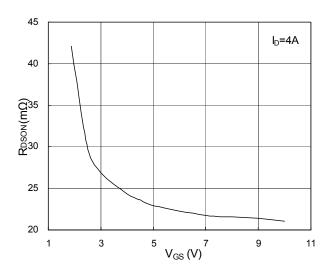


Fig.2 On-Resistance vs. Gate-Source

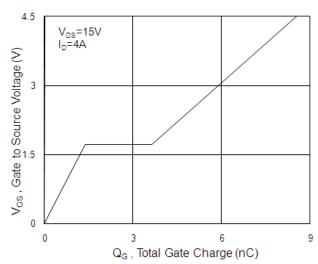


Fig.4 Gate-Charge Characteristics

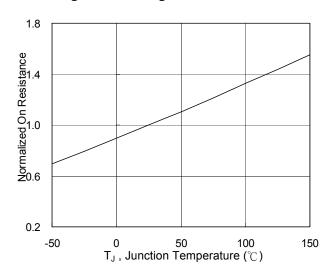
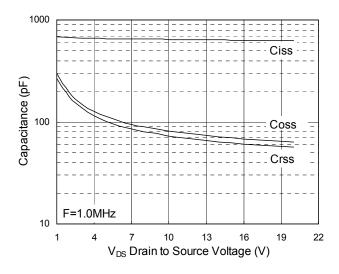


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>



N-Ch MOSFET



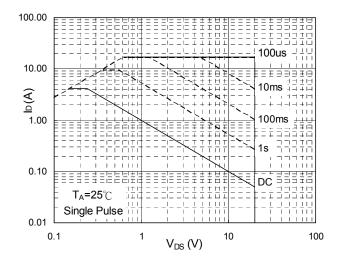


Fig.7 Capacitance

Fig.8 Safe Operating Area

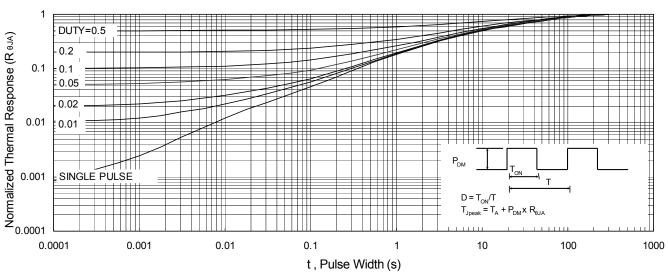
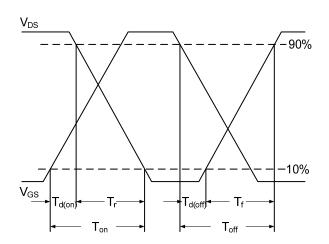


Fig.9 Normalized Maximum Transient Thermal Impedance





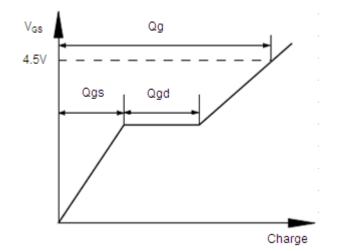


Fig.11 Gate Charge Waveform



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